Appln. No.: 10/088,268 NSG-211US

Amendment Dated March 15, 2004

Reply to Office Action of December 15, 2003

<u>Amendments to the Claims:</u> This listing of claims will replace all prior versions, and listings, of claims in the application

Listing of Claims:

1. - 9. (Canceled)

10. (Currently Amended)

A light-receiving element array, comprising:

a plurality of light-receiving elementspin-photodiodes arrayed in a straight line, each light receiving element of the pin-photodiodes being a pin-photodiode formed by critical crystal growth on a first conductivity-type of substrate, and constituting a mesa and waveguidestructure with the pin-photodiodes

wherein each light-receiving element constitutes a mesa and waveguide-structure with the light-receiving elements being isolated to from each other by isolation trenches;

a first conductivity-type of electrode formed on the bottom surface of the substrate; and

a plurality of second conductivity-type, opposite to the first conductivity-type, electrodes being formed on top surfaces of respective ones of the plurality of pin-photodiode;

wherein light impinges upon end surfaces of the pin-photodiodes, the end surfaces being substantially perpendicular to the second conductivity-type of electrode of the pin-photodiodes.

11. - 12. (Canceled)

- 13. (Currently Amended) The light-receiving element array of claim 11 or 1210, wherein the first conductivity-type is p-type and the second conductivity-type is n-type.
 - 14. (Currently Amended) A light-receiving device, comprising:
 - a light-receiving element array of claim 1210; and

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a circuit board on which the light-receiving element array is mounted, the circuit board including,

a pattern of electrode wirings which are formed in the same pitch as that of the second conductivity-type of electrodes,

a plurality of first leads for the pattern of electrode wirings,

a plurality of first bonding pads connected to the first leads, respectively,

one second bonding pad provided near the light-receiving element array on the circuit board;

a second lead for the second bonding pad, and

a third bonding pad connected to the second lead,

wherein the second conductivity-type of electrodes are connected to the pattern of electrode wirings, and the first conductivity-type of electrode is connected to the second bonding pad.

15. (Original) The light-receiving device of claim 14, wherein the first conductivity-type is p-type and the second conductivity-type is n-type.

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Amendments to the Drawings:

The attached sheet of drawings includes changes to Figure(s) 1-3, 6 and 10. These sheet(s) replace(s) the original sheet(s).

Attachment